

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6108xxxA/BMR-G

Typical Mass: 16 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.197	Silicon	12300	7440-21-3
	-	Arsenic	<1	7440-38-2
Leadframe	5.503	Copper	343900	7440-50-8
	0.022	Tin	1400	7440-31-5
	0.021	Zinc	1300	7440-66-6
	0.024	Chromium	1500	7440-47-3
	0.325	Silver	20300	7440-22-4
Die attach	0.049	Silver	3000	7440-22-4
	0.009	Epoxy	600	—
Bonding wire	0.050	Gold	3100	7440-57-5
Resin	7.680	Silica	480000	60676-86-0
	0.730	Epoxy Resin	45600	—
	0.614	Phenol Resin	38400	—
	0.437	Metal Hydroxide	27300	—
Plating	0.340	Tin	21300	7440-31-5

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."